



Material Content Data Sheet



Sales Product Name		TLE4209A		Issued		28. August 2013		
MA#		MA000982386						
Package		PG-DIP-8-4		Weight*		519.10 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	6.347	1.22	1.22	12226	12226
leadframe	inorganic material	phosphorus	7723-14-0	0.053	0.01		103	
	non noble metal	zinc	7440-66-6	0.213	0.04		411	
	non noble metal	iron	7439-89-6	4.266	0.82		8219	
wire	non noble metal	copper	7440-50-8	173.237	33.37	34.24	333725	342458
	noble metal	gold	7440-57-5	0.611	0.12	0.12	1177	1177
	encapsulation	organic material	carbon black	1333-86-4	1.622	0.31		3124
encapsulation	inorganic material	antimonytrioxide	1309-64-4	6.487	1.25		12496	
	plastics	brominated resin	-	6.487	1.25		12496	
	plastics	epoxy resin	-	66.487	12.81		128082	
	inorganic material	silicondioxide	60676-86-0	243.246	46.87	62.49	468591	624789
leadfinish	non noble metal	tin	7440-31-5	7.496	1.44	1.44	14440	14440
plating	noble metal	silver	7440-22-4	0.832	0.16	0.16	1603	1603
glue	plastics	epoxy resin	-	0.515	0.10		992	
	noble metal	silver	7440-22-4	1.202	0.23	0.33	2315	3307
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com